

PACKAGE: QFN8 1.5 x 1.5 (GREEN)

MATERIALS DECLARATION:

| No. | Part Name | Material Name | Component wt (mg) | Material Content (Element) | CAS Number | Element Wt (%) | Element Wt (mg) | Wt % Of Total Unit Wt | ppm |
|---------------------|---------------------|-----------------|-------------------|--------------------------------|--------------|----------------|-----------------|-----------------------|-----------|
| 1 | Leadframe | Copper (A194) | 1.1521 | Cu | 7440-50-8 | 97.5 | 1.1233 | 32.6759 | 326758.66 |
| | | | | Fe | 7439-89-6 | 2.35 | 0.0271 | 0.7876 | 7875.72 |
| | | | | Zn | 7440-66-6 | 0.12 | 0.0014 | 0.0402 | 402.16 |
| | | | | P | 7723-14-0 | 0.03 | 0.0003 | 0.0101 | 100.54 |
| 2 | Die attach material | Ablebond 8006NS | 0.0319 | Treated silica (5-10) | Proprietary | 9 | 0.0029 | 0.0835 | 835.15 |
| | | | | Glycol ethers (10-30) | Proprietary | 22 | 0.0070 | 0.2041 | 2041.48 |
| | | | | Metal oxide (15-40) | Proprietary | 30 | 0.0096 | 0.2784 | 2783.84 |
| | | | | Curing agent & hardener (5-10) | Proprietary | 9 | 0.0029 | 0.0835 | 835.15 |
| | | | | Epoxy resins (15-40) | Proprietary | 30 | 0.0096 | 0.2784 | 2783.84 |
| 3 | Gold Wire | Gold | 0.0501 | Au | 7440-57-5 | 99.99 | 0.0501 | 1.4586 | 14586.12 |
| 4 | Internal Plating | NiPdAu | 0.0110 | Ni | 7440-02-0 | 92.23 | 0.0101 | 0.2951 | 2951.19 |
| | | | | Pd | 7440-05-3 | 7.48 | 0.0008 | 0.0239 | 239.35 |
| | | | | Au | 7440-57-5 | 0.3 | 0.0000 | 0.0010 | 9.60 |
| 5 | External Plating | NiPdAu | 0.0052 | Ni | 7440-02-0 | 92.22 | 0.0048 | 0.1395 | 1394.96 |
| | | | | Pd | 7440-05-3 | 7.47 | 0.0004 | 0.0113 | 112.99 |
| | | | | Au | 7440-57-5 | 0.31 | 0.00002 | 0.0005 | 4.69 |
| 6 | Mold Compound | EME-G770HCD | 1.9966 | Silica Fused (85 - 95) | 60676-86-0 | 91.7 | 1.8309 | 53.2603 | 532602.98 |
| | | | | Epoxy Resin (1 - 5) | Trade secret | 4 | 0.0799 | 2.3232 | 23232.41 |
| | | | | Phenol Resin (1 - 5) | Trade secret | 4 | 0.0799 | 2.3232 | 23232.41 |
| | | | | Carbon Black (0.1 - 0.5) | 1333-86-4 | 0.3 | 0.0060 | 0.1742 | 1742.43 |
| 7 | Die | Silicon Chip | 0.1907 | | | | 0.1907 | 5.5473 | 55473.17 |
| | | | | | | | | | |
| Total unit weight = | | | 3.4377 | | | | | | |

PACKAGE: SON8 1.5 x 1.0 (GREEN)

MATERIALS DECLARATION:

| No. | Part Name | Material Name | Component wt (mg) | Material Content (Element) | CAS Number | Element Wt (%) | Element Wt (mg) | Wt % Of Total Unit Wt | ppm |
|---------------------|---------------------|---------------------|-------------------|--|--------------|----------------|-----------------|-----------------------|-------------|
| 1 | Leadframe | Copper A194 | 0.7722 | Cu | 7440-50-8 | 97.5 | 0.7529 | 32.9495 | 329494.6731 |
| | | | | Fe | 7439-89-6 | 2.35 | 0.0181 | 0.7942 | 7941.6665 |
| | | | | Zn | 7440-66-6 | 0.12 | 0.0009 | 0.0406 | 405.5319 |
| | | | | P | 7723-14-0 | 0.03 | 0.0002 | 0.0101 | 101.3830 |
| 2 | Die attach material | Screen print 8006NS | 0.0199 | Aluminium Oxide | 1344-28-1 | 50 | 0.0099 | 0.4352 | 4352.0385 |
| | | | | 2-(2-Ethoxyethoxy)ethyl acetate | 112-15-2 | 20 | 0.0040 | 0.1741 | 1740.8154 |
| | | | | Phenol, 4,4'-(1-methylethylidene)bis-,polymer with | 25036-25-3 | 20 | 0.0040 | 0.1741 | 1740.8154 |
| | | | | Epoxy resin | 25068-38-6 | 5 | 0.0010 | 0.0435 | 435.2039 |
| | | | | Aromatic Amine | Proprietary | 5 | 0.0010 | 0.0435 | 435.2039 |
| 3 | Gold Wire | Gold | 0.0147 | Au | 7440-57-5 | 99.99 | 0.0147 | 0.6443 | 6442.7790 |
| | | | | Others | Proprietary | 0.01 | 0.0000 | 0.0001 | 0.6443 |
| 4 | Internal Plating | NiPdAu | 0.0049 | Ni | 7440-02-0 | 92.23 | 0.00450 | 0.1970 | 1969.6335 |
| | | | | Pd | 7440-05-3 | 7.47 | 0.00036 | 0.0160 | 159.5708 |
| | | | | Au | 7440-57-5 | 0.30 | 0.00001 | 0.0006 | 6.4120 |
| 5 | External Plating | NiPdAu | 0.0065 | Ni | 7440-02-0 | 92.23 | 0.0060 | 0.2611 | 2610.9096 |
| | | | | Pd | 7440-05-3 | 7.47 | 0.0005 | 0.0212 | 211.5241 |
| | | | | Au | 7440-57-5 | 0.30 | 0.00002 | 0.0008 | 8.4997 |
| 6 | Mold Compound | EME G770HCD | 1.2963 | Silica Fused | 60676-86-0 | 91.7 | 1.1888 | 52.0258 | 520257.8908 |
| | | | | Epoxy Resin | Trade secret | 4 | 0.0519 | 2.2694 | 22693.9102 |
| | | | | Phenol Resin | Trade secret | 4 | 0.0519 | 2.2694 | 22693.9102 |
| | | | | Carbon Black | 1333-86-4 | 0.3 | 0.0039 | 0.1702 | 1702.0433 |
| 7 | Die | Silicon Die | 0.1704 | | | | 0.1704 | 7.4595 | 74594.9409 |
| Total unit weight = | | | 2.2849 | | | | | | |

REVISION HISTORY

| Revision | Date | Description |
|----------|----------|-----------------|
| A | 4/9/2015 | Initial Release |
| | | |